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Thermally conductive polyethylene resin compsn(s). - comprising lower crystalline copolymer resin(s), and zinc oxide

Patent Assignee: SUMITOMO BAKELITE CO LTD (SUMB)

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Main IPC	Week
JP 9031258	A	19970204	JP 95183033	A	19950719	C08L-023/308	199715 B

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Abstract (Basic): JP 9031258 A

Thermally conductive polyethylene resin compsn(s). (I) comprising (A) and (B) is new. (A) is a lower crystalline copolymer resin(s) with density 0.855-0.890 g/cm³ composed of ethylene (A1) and 3-20C alpha-olefin(s) (A2) (100 pts.wt.). (B) is zinc oxide with ave. particle size 1-15 micrometer prepared by wet process, (20-900 pts.wt.). Thermally conductive polyethylene resin compsn(s). (II) comprising (A) 100 pts.wt., (B) 20-900 pts.wt. and (C) inorganic filler(s) except (B). 10-500 pts.wt. to become (B)+(C) to 910 pts.wt. or less is claimed, also.

USE - (I) and (II) are useful as material for prepn. of thermally conductive sheets to remove heat from IC chips, switching regulators, batteries, etc.

ADVANTAGE - (I) and (II) have excellent thermal conductivity in addition to good mouldability, mechanical strength, dimensional stability and heat resistance.

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